

Title (en)

PIEZOELECTRIC MULTILAYER COMPONENT AND METHOD FOR PRODUCING A PIEZOELECTRIC MULTILAYER COMPONENT

Title (de)

PIEZOELEKTRISCHES VIELSCHICHTBAUELEMENT UND VERFAHREN ZUR HERSTELLUNG EINES PIEZOELEKTRISCHEN VIELSCHICHTBAUELEMENTS

Title (fr)

COMPOSANT MULTICOUCHE PIÉZOÉLECTRIQUE ET PROCÉDÉ DE FABRICATION D'UN COMPOSANT MULTICOUCHE PIÉZOÉLECTRIQUE

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2011101473A1] The invention relates to a piezoelectric multilayer component (1) as an intermediate, which comprises a stack (2) of piezoelectric layers (3) arranged on top of one another. The stack (2) comprises an active region (6) having electrode layers (4) arranged between the piezoelectric layers (3) and at least one inactive region (7), wherein the active region (6) on the end product of the piezoelectric multilayer component (1) is provided for the purpose of deforming when a voltage is applied to the electrode layers (4). The inactive region (7) contains at least one sacrificial layer (8) which comprises an electrically insulating material and a metal, wherein the metal can diffuse at least partially from the sacrificial layer (8) into the piezoelectric layers (3) of the inactive region (7) by heating the multilayer component (1).

IPC 8 full level

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